

Data sheet Product WLP 500



Thermal interface material / Fixing material / Mounting material>Thermal interface material>Thermal conductive paste and thermal interface film silicon-containing thermally conductive paste

Features

material:	silicon thermal transfer compound
composition:	silicone oil, inorganic filling material
basin:	box
specific electrical resistance:	$>10^{12} \Omega/\text{cm}$
flashpoint:	none (DIN 53213)
drop point:	$>260^{\circ}\text{C}$
delivery quantity:	500 g
thermal resistance:	no bleeding at (4 h/200°C)
acid number:	$< 0.01 \text{ mg KOH/g}$
consistance:	pastey
colour:	white
density:	1.1 g/cm^3
thermal conductivity:	$0,61 \text{ W/m}\cdot\text{K}$
temperature range:	$-40^{\circ}\text{C} \dots +250^{\circ}\text{C}$
solubility in water:	insoluble